

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	475	438/464.ccls.	US-PGPUB; USPAT	OR	OFF	2005/08/17 13:14
L3	33	((wafer dic\$6 protective) adj tape) same (release adj tape)	US-PGPUB; USPAT	OR	ON	2005/08/17 14:34
L4	3	((wafer dic\$6 protective) adj tape) and (release adj tape)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/17 14:37
L7	55	(438/108.ccls. 438/113.ccls. 438/114.ccls. 438/459.ccls. 438/461.ccls. 438/464.ccls. 438/465.ccls. 438/977.ccls. 29/740.ccls. 29/743.ccls. 156/584.ccls.) and (dbg (dic\$6 near2 grind\$6))	US-PGPUB; USPAT	OR	ON	2005/08/17 14:37
L8	12	"6297131".URPN.	USPAT	OR	OFF	2005/08/17 14:37
L9	127	((dbg (dic\$6 near2 grind\$6))) and (semiconductor wafer package chip ic integrated die dice silicon tape)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/17 14:39
L10	178	((438/108.ccls. 438/113.ccls. 438/114.ccls. 438/459.ccls. 438/461.ccls. 438/464.ccls. 438/465.ccls. 438/977.ccls. 29/740.ccls. 29/743.ccls. 156/584.ccls.) and ((wafer dic\$6 protect\$6 releas\$6) adj tape)) and (((die chip) adj pad) leadframe (lead adj frame) ((uv ultraviolet) with adhe\$8))	US-PGPUB; USPAT	OR	ON	2005/08/17 14:40
L11	44	"5480842".URPN.	USPAT	OR	OFF	2005/08/17 14:41
L13	7	((wafer dic\$6 protect\$6 releas\$6) adj tape) same (((die chip) adj pad) with (leadframe (lead adj frame) (((package wiring) adj substrate) carrier) with (solder adj ball))))	US-PGPUB; USPAT	OR	ON	2005/08/17 14:43
L14	0	((wafer dic\$6 protect\$6 releas\$6) adj tape) same ((die chip) adj pad) same (leadframe (lead adj frame)) same (((package wiring) adj substrate) carrier module) with (solder adj ball))	US-PGPUB; USPAT	OR	ON	2005/08/17 14:45
L15	2	((die chip) adj pad) same (leadframe (lead adj frame)) same (((package wiring) adj substrate) carrier module) with (solder adj ball))	US-PGPUB; USPAT	OR	ON	2005/08/17 15:26

L16	0	(438/108.ccls. 438/113.ccls. 438/114.ccls. 438/459.ccls. 438/461.ccls. 438/464.ccls. 438/465.ccls. 438/977.ccls. 29/740.ccls. 29/743.ccls. 156/584.ccls.) and ((protective adj tape) with (thermal adj degradation))	US-PGPUB; USPAT	OR	ON	2005/08/17 14:57
L17	1	((protective adj tape) same (thermal adj degradation))	US-PGPUB; USPAT	OR	ON	2005/08/17 14:58
L18	1	(438/108.ccls. 438/113.ccls. 438/114.ccls. 438/459.ccls. 438/461.ccls. 438/464.ccls. 438/465.ccls. 438/977.ccls. 29/740.ccls. 29/743.ccls. 156/584.ccls.) and ((protect\$6 adj tape) with adhe\$8 with (weaken degrad\$8) with heat\$6)	US-PGPUB; USPAT	OR	ON	2005/08/17 14:58
L19	1	(438/108.ccls. 438/113.ccls. 438/114.ccls. 438/459.ccls. 438/461.ccls. 438/464.ccls. 438/465.ccls. 438/977.ccls. 29/740.ccls. 29/743.ccls. 156/584.ccls.) and ((protect\$6 adj tape) same adhe\$8 same (weaken degrad\$8) same heat\$6)	US-PGPUB; USPAT	OR	ON	2005/08/17 14:58
L21	1	(438/108.ccls. 438/113.ccls. 438/114.ccls. 438/459.ccls. 438/461.ccls. 438/464.ccls. 438/465.ccls. 438/977.ccls. 29/740.ccls. 29/743.ccls. 156/584.ccls.) and ((protect\$6 adj tape) same (adhe\$8 bond\$6) same (weaken degrad\$8) same (heat\$6 thermal\$4 temperature))	US-PGPUB; USPAT	OR	ON	2005/08/17 14:58
L25	21	(438/108.ccls. 438/113.ccls. 438/114.ccls. 438/459.ccls. 438/461.ccls. 438/464.ccls. 438/465.ccls. 438/977.ccls. 29/740.ccls. 29/743.ccls. 156/584.ccls.) and ((protect\$6 adj tape) same (adhe\$8 bond\$6) same (heat\$6 thermal\$4 temperature))	US-PGPUB; USPAT	OR	ON	2005/08/17 14:58